

What is claimed is:

9/29/2004

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Foreign 10/22/2003

[Claim 1] A multilayer wiring board adapted to receive a semiconductor chip to be soldered thereto, comprising:

an insulating layer;

a plurality of electrode pads provided on said insulating layer so that each of said electrode pads is located corresponding to an associated one of a plurality of solder bumps of the semiconductor chip to be soldered;

a solder resist covering said insulating layer and said electrode pads;

openings provided in said solder resist covering said electrode pads, each of said openings reaching a surface of the electrode pad; and

solder filled into the openings of said solder resist,

wherein each of the electrode pads corresponding to the solder bumps located near an outer periphery of the semiconductor chip to be soldered has an oblong shape,

each of the openings of said solder resist is smaller than said oblong shape, and

a center of said opening is located to be offset from a center of said oblong shape in a direction toward a center of the semiconductor chip to be soldered.

[Claim 2] A multilayer wiring board according to claim 1, wherein each of the electrode pads corresponding to the solder bumps located near said outer periphery has an oval shape, and each of the openings of said solder resist has a circular shape.

[Claim 3] A multilayer wiring board with a semiconductor chip mounted thereon, comprising:

an insulating layer;

a plurality of electrode pads on said insulating layer;

a solder resist cover said insulating layer and said electrode pads;

openings provided in said solder resist covering said electrode pads, each of said openings reaching a surface of the electrode pad;

the semiconductor chip having a plurality of electrodes each arranged to correspond to an associated one of said electrode pads; and

solder joints filling said openings, respectively, each of said solder joints connecting the corresponding one of said electrode pads to the corresponding one of said electrodes of said semiconductor chip,

wherein each of the electrode pads corresponding to the electrodes located near an outer periphery of said semiconductor chip has an oblong shape,

each of the openings of said solder resist is smaller than said oblong shape, and

a center of said opening is located to be offset from a center of said oblong shape in a direction toward a center of said semiconductor chip.

[Claim 4] A multilayer wiring board according to claim 3, wherein each of the electrode pads corresponding to the electrodes located near said outer periphery has an oval shape, and each of the openings of said solder resist has a circular shape.